

ABSTRACT OF THE DISCLOSURE

A semiconductor chip package includes a semiconductor chip mounted on a top surface of a substrate. A bottom surface of the substrate has ball pads. Bonding pads of the chip are electrically connected to the substrate. Enhanced pads, each having one or more dummy patterns coupled to one or more dummy pads, are preferably formed near edges of the substrate. The semiconductor chip package is mounted on the board by attaching external connection terminals such as solder balls, formed on the ball pads and the dummy pads, to a solder paste coated on ball lands and enhanced lands of the board.